

**IN THE CLAIMS:**

We claim:

1           1.       A memory system comprising a plurality of T-RAM cells arranged in an array,  
2       wherein each of the plurality of T-RAM cells includes a thyristor region beneath at least a  
3       portion of a transfer gate region.

1           2.       The memory system according to Claim 1, wherein the thyristor region  
2       includes a buried vertical thyristor and the transfer gate region includes a horizontally  
3       stacked pseudo-TFT transfer gate.

1           3.       The memory system according to Claim 1, wherein each of the plurality of T-  
2       RAM cells has a size of less than or equal to  $8F^2$ .

1           4.       The memory system according to Claim 1, wherein the plurality of T-RAM  
2       cells are fabricated on a semiconductor SOI or bulk wafer.

1           5.       The memory system according to Claim 1, wherein a base of the thyristor  
2       region is surrounded by a vertical surrounded gate.

1           6.       The memory system according to Claim 5, wherein the vertical surrounded  
2       gate contacts a wordline.

1           7.       The memory system according to Claim 1, wherein the thyristor region and  
2       the transfer gate region are connected by a lateral epitaxial grown  $n^+$  region.

1           8.       The memory system according to Claim 2, wherein a bitline contacts a  
2       junction of the stacked pseudo-TFT transfer gate.

1           9.       The memory system according to Claim 2, wherein the stacked pseudo-TFT  
2       transfer gate contacts a wordline.

1           10.     The memory system according to Claim 1, wherein each of the plurality of T-  
2 RAM cells includes structure for the traversal of at least two wordlines there through.

1           11.     The memory system according to Claim 2, wherein a vertical surrounded gate  
2 is aligned with a base region of the buried vertical thyristor.

1           12.     A T-RAM array comprising:  
2           a plurality of T-RAM cells, wherein each of the plurality of T-RAM cells includes a  
3 thyristor region beneath at least a portion of a transfer gate region.

1           13.     The array according to Claim 12, wherein the thyristor region includes a  
2 buried vertical thyristor and the transfer gate region includes a horizontally stacked pseudo-  
3 TFT transfer gate.

1           14.     The array according to Claim 12, wherein each of the plurality of T-RAM  
2 cells has a size of less than or equal to  $8F^2$ .

1           15.     The array according to Claim 12, wherein the plurality of T-RAM cells are  
2 fabricated on a semiconductor SOI or bulk wafer.

1           16.     The array according to Claim 12, wherein a base of the thyristor region is  
2 surrounded by a surrounded gate.

1           17.     The array according to Claim 12, wherein each of the plurality of T-RAM  
2 cells includes structure for the traversal of at least two wordlines there through.

1           18.     A method for fabricating a T-RAM array having a plurality of T-RAM cells,  
2 the method comprising the steps of:  
3           providing a semiconductor wafer;  
4           fabricating a thyristor region having a thyristor for each of the plurality of T-RAM  
5 cells over the semiconductor wafer; and

1 fabricating a surrounded gate for each of the plurality of T-RAM cells, wherein the  
2 surrounded gate is aligned with a base region of the thyristor;

3 fabricating a transfer gate region having a transfer gate for each of the plurality of T-  
4 RAM cells over at least a portion of the thyristor region.

1 19. The method according to Claim 18, wherein each of the plurality of T-RAM  
2 cells has a size of less than or equal to  $8F^2$ .

1 20. The method according to Claim 18, wherein the semiconductor wafer is a  
2 semiconductor SOI or bulk wafer.

1 21. The method according to Claim 18, wherein the thyristor is a vertical thyristor  
2 and the transfer gate is a pseudo-TFT transfer gate.

1 22. The method according to Claim 18, further comprising the step of fabricating  
2 first and second wordlines, wherein the first wordline contacts the surrounded gate and the  
3 second wordline is integral with the transfer gate.

1 23. The method according to Claim 18, further comprising the step of fabricating  
2 a plurality of bitline contacts throughout the T-RAM array; and

3 fabricating a plurality of bitlines and a plurality of bitline contacts contacting a  
4 respective one of the plurality of bitlines, wherein each of the plurality of bitline contacts  
5 connects the respective one of the plurality of bitlines to a junction of the transfer gate.

1 24. The method according to Claim 18, further comprising the step of providing  
2 three layers on the semiconductor wafer prior to the step of fabricating the thyristor region,  
3 wherein a first layer is provided on top of a buried oxide layer and is a p-type layer and a  
4 second layer is provided on top of the first layer, said second layer is a nitride-oxide layer  
5 having a nitride layer below an oxide layer.

1           25.     The method according to Claim 24, wherein the step of fabricating the  
2 thyristor region having the thyristor for each of the plurality of T-RAM cells over the  
3 semiconductor wafer includes the steps of:  
4           providing a mask over the semiconductor wafer;  
5           etching the oxide layer of the second layer to form etched regions over the nitride  
6 layer;  
7           depositing polysilicon within the etched regions;  
8           etching the polysilicon to form a pair of spacer gates for each of the plurality of T-  
9 RAM cells;  
10          etching the nitride layer of the second layer to the surface of the first layer to shape  
11 the thyristor region; and  
12          growing an n-p-n layer within the thyristor region to form the thyristor.

1           26.     The method according to Claim 25, wherein the step of growing the n-p-n  
2 layer includes the steps of:  
3           fabricating a first n-type layer over the first layer using a first n-type doping implant;  
4           fabricating an p-type layer over the first n-type layer using a p-type doping implant;  
5 and  
6           fabricating a second n-type layer over the p-type layer by using a second n-type  
7 doping implant.

1           27.     The method according to Claim 26, wherein the step of fabricating the first n-  
2 type layer includes the step of using n-type doping with a dosage of between  $2E13/cm^2$  and  
3  $8E14/cm^2$ ; wherein the step of fabricating the p-type layer includes the step using a p-type  
4 doping with a dosage of between  $4E13/cm^2$  and  $1E14/cm^2$ ; and wherein the step of  
5 fabricating the second n-type layer includes the step of using an n-type doping with a dosage  
6 of between  $8E14/cm^2$  and  $3E15/cm^2$ .

1           28.     The method according to Claim 18, wherein the step of fabricating the  
2 transfer gate region having the transfer gate for each of the plurality of T-RAM cells over at  
3 least a portion of the thyristor region includes the steps of:

1 fabricating an epi layer over the thyristor region;  
2 providing a dielectric film over the epi layer;  
3 depositing an insulating film over the dielectric film;  
4 forming two gates within the insulating film; and  
5 implanting an n<sup>+</sup> dopant within the epi layer to form source and drain regions for the  
6 transfer gate.

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